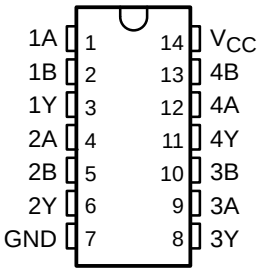
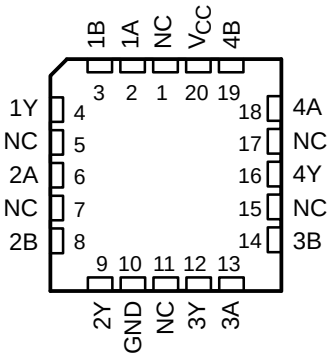
- **Package Options Include Plastic Small-Outline (D) and Ceramic Flat (W) Packages, Ceramic Chip Carriers (FK), and Standard Plastic (N) and Ceramic (J) 300-mil DIPs**

SN54HC03 . . . J OR W PACKAGE
SN74HC03 . . . D OR N PACKAGE
(TOP VIEW)



SN54HC03 . . . FK PACKAGE
(TOP VIEW)



NC – No internal connection

description

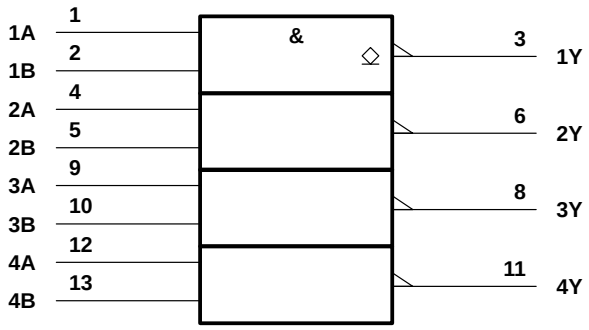
These devices contain four independent 2-input NAND gates. They perform the Boolean function $Y = \overline{A \bullet B}$ or $Y = \overline{A} + \overline{B}$ in positive logic. The open-drain outputs require pullup resistors to perform correctly. They may be connected to other open-drain outputs to implement active-low wired-OR or active-high wired-AND functions.

The SN54HC03 is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74HC03 is characterized for operation from –40°C to 85°C.

FUNCTION TABLE
(each gate)

INPUTS		OUTPUT
A	B	Y
H	H	L
L	X	H
X	L	H

logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.
Pin numbers shown are for the D, J, N, and W packages.

logic diagram (positive logic)

Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

absolute maximum ratings over operating free-air temperature range†

Supply voltage range, V_{CC} . . . . . –0.5 V to 7 V
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$) (see Note 1) . . . . . ±20 mA
Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{CC}$) (see Note 1) . . . . . ±20 mA
Continuous output current, I_O ($V_O = 0$ to V_{CC}) . . . . . ±25 mA
Continuous current through V_{CC} or GND . . . . . ±50 mA
Package thermal impedance, θ_{JA} (see Note 2): D package . . . . . 127°C/W
N package . . . . . 78°C/W
Storage temperature range, T_{stg} . . . . . –65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
2. The package thermal impedance is calculated in accordance with JESD 51, except for through-hole packages, which use a trace length of zero.

recommended operating conditions

			SN54HC03			SN74HC03			UNIT
			MIN	NOM	MAX	MIN	NOM	MAX	
V_{CC}	Supply voltage		2	5	6	2	5	6	V
V_{IH}	High-level input voltage	V_{CC} = 2 V	1.5			1.5			V
		V_{CC} = 4.5 V	3.15			3.15			
		V_{CC} = 6 V	4.2			4.2			
V_{IL}	Low-level input voltage	V_{CC} = 2 V	0		0.5	0		0.5	V
		V_{CC} = 4.5 V	0		1.35	0		1.35	
		V_{CC} = 6 V	0		1.8	0		1.8	
V_I	Input voltage		0		V_{CC}	0		V_{CC}	V
V_O	Output voltage		0		V_{CC}	0		V_{CC}	V
t_t	Input transition (rise and fall) time	V_{CC} = 2 V	0		1000	0		1000	ns
		V_{CC} = 4.5 V	0		500	0		500	
		V_{CC} = 6 V	0		400	0		400	
T_A	Operating free-air temperature		–55		125	–40		85	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS		V_{CC}	T_A = 25°C			SN54HC03		SN74HC03		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
I_{OH}	$V_I = V_{IH}$ or V_{IL}, $V_O = V_{CC}$		6 V		0.01	0.5		10		5	µA
V_{OL}	$V_I = V_{IH}$ or V_{IL}	I_{OL} = 20 µA	2 V		0.002	0.1		0.1		0.1	V
			4.5 V		0.001	0.1		0.1		0.1	
			6 V		0.001	0.1		0.1		0.1	
		I_{OL} = 4 mA	4.5 V		0.17	0.26		0.4		0.33	
		I_{OL} = 5.2 mA	6 V		0.15	0.26		0.4		0.33	
I_I	$V_I = V_{CC}$ or 0		6 V		±0.1	±100		±1000		±1000	nA
I_{CC}	$V_I = V_{CC}$ or 0, $I_O = 0$		6 V			2		40		20	µA
C_i			2 V to 6 V		3	10		10		10	pF

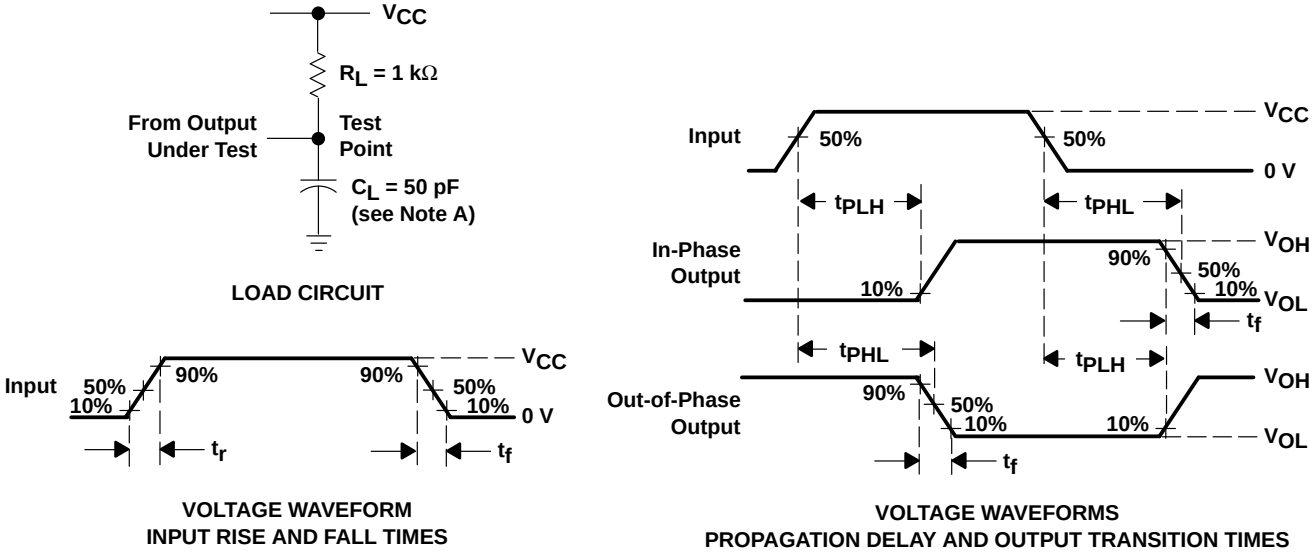
switching characteristics over recommended operating free-air temperature range, C_L = 50 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC}	T_A = 25°C			SN54HC03		SN74HC03		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t_{PLH}	A or B	Y	2 V		60	105		155		131	ns
			4.5 V		13	25		36		31	
			6 V		10	23		31		27	
t_{PHL}	A or B	Y	2 V		50	100		150		125	ns
			4.5 V		10	20		30		25	
			6 V		8	17		25		21	
t_f		Y	2 V		38	75		110		95	ns
			4.5 V		8	15		22		19	
			6 V		6	13		19		16	

operating characteristics, T_A = 25°C

PARAMETER		TEST CONDITIONS	TYP	UNIT
C_{pd}	Power dissipation capacitance per gate	No load	20	pF

PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and test-fixture capacitance.
B. Phase relationships between waveforms were chosen arbitrarily. All input pulses are supplied by generators having the following characteristics: PRR ≤ 1 MHz, Z_O = 50 Ω, t_r = 6 ns, t_f = 6 ns.
C. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

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